

Claims

1. Component for a circuit board (32), having a housing (10) on which at least one peg (28) is designed for engaging in a hole (30) in the circuit board (32), whereby
5 the peg (28) has at least one detent lug (52) which projects in the radial direction relative to the peg (28) beyond its outer periphery, characterised in that the detent lug (52) is designed and arranged on the peg (28)
10 such that the outer periphery of the peg (28) is smaller in the region of the detent lug (52) than the diameter of the hole (30) in the circuit board (32), whereby the outer periphery of the section of the peg (28) protruding into the hole (30) in the circuit board (32) is designed such
15 that between the outer periphery of this section and the inner wall of the hole (30) in the circuit board (32), over at least a portion of the outer periphery there is an intermediate space with capillarity for solder, such that solder (50) situated on the surface of the circuit board
20 (32) during a soldering procedure penetrates by capillary action into the intermediate space, filling it.

2. Component according to claim 1, characterised in that the detent lug (52) is designed and arranged on the peg (28) such that with the component placed fully on the
25 circuit board (32), the detent lug (52) is arranged within the hole (30) in the circuit board (32).

3. Component according to claim 1 or 2, characterised in that the periphery of the peg (28) in the longitudinal direction over the whole section situated in the hole (30)
30 in the circuit board (32) is designed with at least one cut-out (54).

4. Component according to at least one of the preceding claims, characterised in that the hole (30) in the circuit board (32) is metallised.

5. Component according to at least one of the preceding claims, characterised in that the peg is made of plastics.

6. Method for inserting a component into a circuit board designed according to at least one of the preceding claims, characterised by application of soldering paste on the circuit board round at least a portion of the periphery of the hole, placement of the component into said circuit board with the peg in the hole in said circuit board, heating of the solder arranged round the hole such that the solder penetrates by capillary action into the intermediate space with capillarity, and cooling of the solder which has penetrated into the hole, such that it hardens.